

Title (en)

METHOD AND DEVICE FOR TREATING SUBSTRATES

Title (de)

VERFAHREN UND VORRICHTUNG ZUM BEHANDELN VON SUBSTRATEN

Title (fr)

PROCEDE ET DISPOSITIF POUR TRAITER DES SUBSTRATS

Publication

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Application

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Abstract (en)

[origin: DE19948630A1] The aim of the invention is to easily and cost-effectively prevent substrates from being damaged by virtue of long sojourn times in a treatment fluid. The present invention relates to a method for treating substrates, especially semiconductor wafers in a treatment basin that is filled with a treatment fluid. A fluid which dilutes the treatment fluid is inserted into the treatment basin when malfunctioning occurs. The invention also relates to a corresponding device for treating substrates.

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